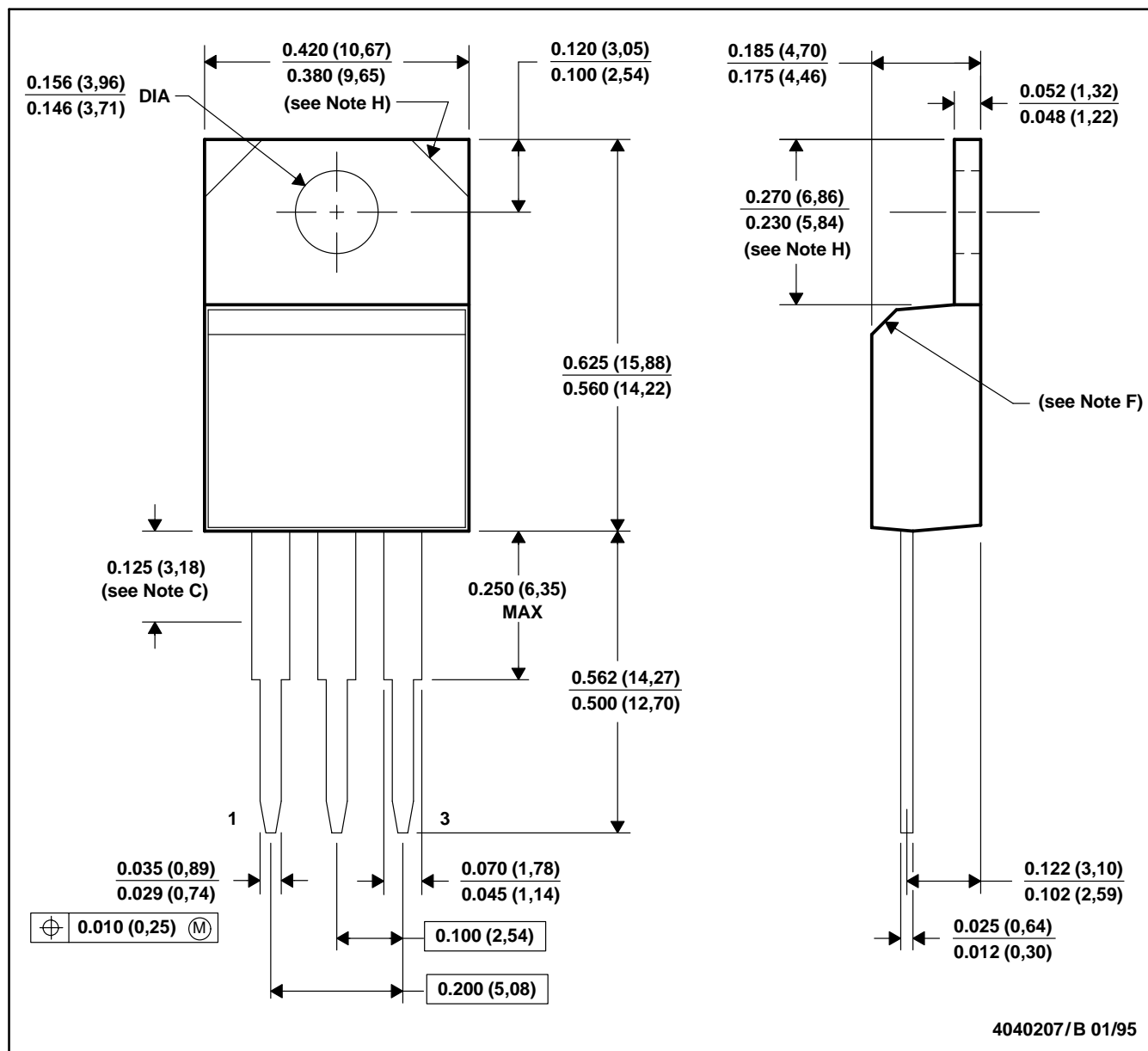


## KC (R-PSFM-T3)

## PLASTIC FLANGE-MOUNT PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Lead dimensions are not controlled within this area.  
 D. All lead dimensions apply before solder dip.  
 E. The center lead is in electrical contact with the mounting tab.  
 F. The chamfer is optional.  
 G. Falls within JEDEC TO-220AB  
 H. Tab contour optional within these dimensions

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